

~~DO NOT ENTER: /MS/~~

~~02/07/2008~~

**PATENT APPLICATION**

**RESPONSE UNDER 37 CFR §1.116  
EXPEDITED PROCEDURE  
TECHNOLOGY CENTER ART UNIT 1792**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**In re the Application of**

**Shigehiro NISHINO et al.**

**Group Art Unit: 1792**

**Application No.: 10/520,141**

**Examiner: M. SONG**

**Filed: September 1, 2005**

**Docket No.: 122261**

**For: LARGE-DIAMETER SIC WAFER AND MANUFACTURING METHOD THEREOF**

**AMENDMENT AFTER FINAL REJECTION UNDER 37 CFR §1.116**

**Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450**

**Sir:**

**In reply to the November 26, 2007 Office Action, please consider the following:**

**Amendments to the Claims** as reflected in the listing of claims; and

**Remarks.**

*ENTERED BY  
RCE  
3/20/08  
HBT*